

## WHAT IS CLAIMED IS:

1. A solid electrolytic capacitor comprising:  
an anode composed of a metal;  
5 a dielectric layer composed of an oxide of said metal  
and formed on the surface of said anode; and  
a metal layer formed on the surface of said dielectric  
layer.
- 10 2. The solid electrolytic capacitor according to Claim  
1, wherein  
said metal layer is composed of metal particles.
- 15 3. The solid electrolytic capacitor according to Claim  
2, wherein  
an average particle diameter of said metal particles is  
not larger than 0.05  $\mu$ m.
- 20 4. The solid electrolytic capacitor according to Claim  
2, wherein  
said average particle diameter of said metal particles  
is not smaller than 0.01  $\mu$ m.
- 25 5. The solid electrolytic capacitor according to Claim  
2, wherein

said metal particles include at least one kind of metal selected from the group consisting of silver, gold, and platinum.

5           6. The solid electrolytic capacitor according to Claim 1, wherein

              said metal layer includes a protective colloid.

10          7. The solid electrolytic capacitor according to Claim 1, wherein

              said metal layer is composed of a metal plated layer.

8. The solid electrolytic capacitor according to Claim 1, wherein

15          said anode includes at least one kind of metal selected from the group consisting of tantalum, aluminum, niobium, and titanium.

20          9. A method of manufacturing a solid electrolytic capacitor including the steps of:

              forming on the surface of an anode composed of a metal a dielectric layer composed of an oxide of said metal; and forming a metal layer on said dielectric layer.

25          10. The method of manufacturing a solid electrolytic

capacitor according to Claim 9, wherein  
said step of forming said metal layer includes the step  
of forming said metal layer by metal particles.

5 11. The method of manufacturing a solid electrolytic  
capacitor according to Claim 10, wherein  
an average particle diameter of said metal particles is  
not larger than 0.05 µm.

10 12. The method of manufacturing a solid electrolytic  
capacitor according to Claim 10, wherein  
said average particle diameter of said metal particles  
is not smaller than 0.01 µm.

15 13. The method of manufacturing a solid electrolytic  
capacitor according to Claim 10, wherein  
said step of forming said metal layer includes the steps  
of:

20 applying a metal paste including said metal particles  
on said dielectric layer; and  
drying said metal paste at a temperature of 150°C or higher  
after applying said metal paste.

25 14. The method of manufacturing a solid electrolytic  
capacitor according to Claim 10, wherein

said step of forming said metal layer including the steps  
of:

preparing a metal paste by mixing said metal particles  
and a protective colloid in an organic solvent; and

5 applying said metal paste on the surface of said  
dielectric layer.

15. The method of manufacturing a solid electrolytic  
capacitor according to Claim 9, wherein

10 said step of forming said metal layer includes the step  
of forming said metal layer by metal plating.